

Wired Interface Market - Forecasts From 2018 to 2023

<https://marketpublishers.com/r/W47C6D726DFEN.html>

Date: December 2018

Pages: 105

Price: US\$ 3,950.00 (Single User License)

ID: W47C6D726DFEN

Abstracts

The Wired Interface Market is projected to grow at a CAGR of 12.50% to reach US\$33.268 billion by 2023, from US\$16.406 billion in 2017. The wired interface technology deals with the transfer of data, power, audio and video with the use of cables. Different types of cables are manufactured based on purpose and security. The wired interface technology market will grow on account of increasing worldwide dependence on electronics such as smartphones, computers, projectors and more. The demand for wired interface technology will also rise because of rising security concerns and higher data transferability advantages that it provides. However, the trend towards the adoption of wireless technology will be a restraining factor for the growth of the wired interface market. The North American region is at a mature stage due to the early adoption of technology. The Asia Pacific region will grow significantly with the improvement in the standard of living resulting in increased demand for smartphones, PCs and other consumer electronics.

This research study examines the current market trends related to the demand, supply, and sales, in addition to the recent developments. Major drivers, restraints, and opportunities have been covered to provide an exhaustive picture of the market. The analysis presents in-depth information regarding the development, trends, and industry policies and regulations implemented in each of the geographical regions. Further, the overall regulatory framework of the market has been exhaustively covered to offer stakeholders a better understanding of the key factors affecting the overall market environment.

Identification of key industry players in the industry and their revenue contribution to the overall business or relevant segment aligned to the study have been covered as a part of competitive intelligence done through extensive secondary research. Various studies and data published by industry associations, analyst reports, investor presentations, press releases and journals among others have been taken into consideration while

conducting the secondary research. Both bottom-up and top down approaches have been utilized to determine the market size of the overall market and key segments. The values obtained are correlated with the primary inputs of the key stakeholders in the wired interface value chain. The last step involves complete market engineering which includes analyzing the data from different sources and existing proprietary datasets while using various data triangulation methods for market breakdown and forecasting.

Market intelligence is presented in the form of analysis, charts, and graphics to help the clients in gaining faster and efficient understanding of the Wired Interface market.

Major industry players profiled as part of the report Molex, LLC., Amphenol Corporation, Japan Aviation Electronics Industry, Ltd., TE Connectivity, STMicroelectronics N.V., among others.

Segmentation

The Wired Interface market has been analyzed through following segments:

By Component

Data Transfer Interface

Power Transfer Interface

Audio and Display Interface

Others

By Device

Smartphones and Tablets

Personal Computers and Laptops

Entertainment Devices

Audio and Video Output Devices

External Data Storage Devices

Others

By Geography

North America

USA

Canada

Mexico

Others

South America

Brazil

Argentina

Others
Europe
Germany
France
United Kingdom
Spain
Others
Middle East and Africa
Saudi Arabia
Israel
Others
Asia Pacific
China
Japan
South Korea
India
Others

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